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## (54) SEMICONDUCTOR DEVICE, INSULATING LAMINATE USED THEREFOR, AND MANUFACTURE OF THE DEVICE

(57)Abstract:

**PURPOSE:** To enable the insulating board of an insulating laminate to be protected against cracks or fissure and enhanced in conductive properties.

**CONSTITUTION:** A molybdenum plate 15 larger than a copper plate 8 of an insulating laminate 12 in hardness is fixed to the outer surface of the copper plate 8. Thermal expansion is induced when the heat is released from a semiconductor element 4 in operation to cause a slide at an interface between the plates 8 and 15, whereby micro-irregularities are prevented from being formed at the interface. By this setup, stress induced by applying pressure onto an aluminum nitride board 7 is dispersed throughout all the board 7 so as to protect the board 7 against cracks or fissure.

